

Automotive Electronics Council

Component Technical Committee

Agenda (subject to change)

2025 - Fourth European
Automotive Electronics
Reliability Workshop

October 8 & 9

Bordeaux, France
Palais de la Bourse

Wednesday October 8, 2025

08:00 AM - 08:30 AM	Registration					
08:30 AM - 09:00 AM	O	Welcome & AEC Updates		Rene Rongen	NXP Semiconductors	
09:00 AM - 10:30 AM	Technical Session 1: Passives, LEDs, WBG					
09:00 AM - 09:30 AM	T1.1	Tantalum Polymer Capacitors Trends and Challenges - Software Defined Vehicles (SDV)		Moderator: Uwe Berger	Hella (Forvia)	
09:30 AM - 10:00 AM	T1.2	Need for speed? A Comparative Study of H2S-Corrosion Tests		Cristina MotaCaetano	Yageo	
10:00 AM - 10:30 AM	T1.3	HVM "Golden Recipe" Methodology for SiC Substrate Qualification Across Suppliers		Jennifer Rieder	amsOSRAM	
				Jay Rathert, Michael Schmalz	KLA / VW	
10:30 AM - 11:00 AM	Break					
11:00 AM - 11:30 AM	Technical Session 2: Invited Paper				Moderator: René Rongen	NXP Semiconductors
11:00 AM - 11:30 AM	T2.1	SAFETY in cars		Franck Gallie	NXP Semiconductors	
11:30 AM - 12:00 PM	W1	Q102 / Optoelectronics		Uwe Berger	Hella (Forvia)	
12:00 PM - 12:30 PM	W2	Q200		Alan Cooper	Yageo	
12:30 PM - 01:30 PM	Lunch					
01:30 PM - 02:00 PM	W3	Q101 / Discretes		Andreas Pinkernelle	Nexperia	
02:00 PM - 02:45 PM	W4	Wide Band Gap		Massimiliano Regardi	Nexperia	
02:45 PM - 03:45 PM	Technical Session 3: Power Modules				Moderator: Martin Geiger	Microchip
02:45 PM - 03:15 PM	T3.1	Advanced Estimation of Remaining Useful Lifetime for Power Modules		Horst Lewitschnig	Infineon Technologies Austria AG	
03:15 PM - 03:45 PM	T3.2	Thermal Fatigue in Copper Wire Bonds under Power Cycling: Acceleration Model and Influence of Different Wire Types		Carlo Neva	STMicroelectronics	
03:45 PM - 04:15 PM	Break					
04:15 PM - 4:45 PM	Technical Session 3: Power Modules (cont'd)				Moderator: Martin Geiger	Microchip
04:15 PM - 04:45 PM	T3.3	New HAST and non-destructive evaluation methods for Power Modules		Etienne Wortham	Zestron	
04:45 PM - 05:00 PM	W5	Q007 / Board Level Reliability		Romuald Roucou	NXP Semiconductors	
05:00 PM - 05:30 PM	Technical Session 4: Board Level				Moderator: Romuald Roucou	NXP Semiconductors
05:00 PM - 05:30 PM	T4.1	Implementing High-Temperature Lead-Free Solder Paste for Power Discrete Applications - Readiness & Challenges		H Zhang	Indium	
05:30 PM	Wrap-up Day 1					

Thursday October 9, 2025

08:15 AM - 08:30 AM	O	Welcome	Rene Rongen	NXP Semiconductors
08:30 AM - 09:00 AM	W6	Extend Mission Profiles	Rene Rongen	NXP Semiconductors
09:00 AM - 10:30 AM	Technical Session 5: Extended/ Severe Mission Profiles		Moderator: Claudia Maria Palumbiny	Infineon Technologies
09:00 AM - 09:30 AM	T5.1	Extended Lifetime Evaluation – An OEM Point of View	Stefan Simon	Audi
09:30 AM - 10:00 AM	T5.2	Rethinking "Automotive": How to Specify Components for Tomorrow's Mobility	Francois Gouyou	Valeo
10:00 AM - 10:30 AM	T5.3	Considerations and Challenges in the Use of AEC-Q Components for Space Missions	Gonzalo Fernandez; Anastasia Pesce	Alter Technology / ESA
10:30 AM - 11:00 AM	Break			
11:00 AM - 11:30 AM	W7	Q004 / Zero Defects & Q006 / Cu-wire	Rene Rongen	NXP Semiconductors
11:30 AM - 12:30 PM	Technical Session 6: Zero Defects		Bassel Atala	STMicroelectronics
11:30 AM - 12:00 PM	T6.1	Advancing Zero Defect Through Process-Oriented Reliability and Soft Error Risk Integration	Calvin Yang	SGS
12:00 AM - 12:30 PM	T6.2	Technical cleanliness for electronic components	Uwe Berger	Hella (Forvia)
12:30 PM - 01:30 PM	Lunch			
01:30 PM - 02:00 PM	W8	Q100 IC & CDC Template	Claudia Maria Palumbiny	Infineon Technologies
02:00 PM - 03:00 PM	Technical Session 7: Zero Defects / Memory		Moderator: Martin Geiger	Microchip
02:00 PM - 02:30 PM	T7.1	Outliers Detection for Zero Defect on Non-Normal and Highly Multivariate Data	Francois Bergeret; Francois Bourlon	Ippon Innovation / NXP Semiconductors
02:30 PM - 03:00 PM	T7.2	Reliability Assessment of Single-Ended PCM in Automotive Microcontrollers Compliant with AEC-Q100 Standards	Fabio Dellorto	STMicroelectronics
03:00 PM - 03:30 PM	Break			
03:30 PM - 04:00 PM	Technical Session 8: ESD		Moderator: René Rongen	NXP Semiconductors
03:30 PM - 04:00 PM	T8.1	New Contact-Based CDM Methods Needed to Align with ESD Roadmap	Greg O'Sullivan	Micron
04:00 PM - 04:15 PM	W9	Q104 / MCMs	Rene Rongen	NXP Semiconductors
04:15 PM	Wrap-up Day 2 and Closure			